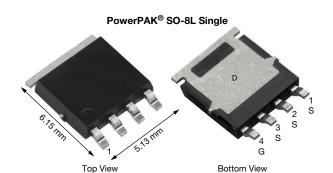


N-Channel 60 V (D-S) MOSFET



| PRODUCT SUMMARY | |
|--|--------|
| V _{DS} (V) | 60 |
| $R_{DS(on)}$ max. (Ω) at $V_{GS} = 10 \text{ V}$ | 0.0045 |
| $R_{DS(on)}$ max. (Ω) at $V_{GS} = 7.5 \text{ V}$ | 0.0054 |
| $R_{DS(on)}$ max. (Ω) at $V_{GS} = 6 \text{ V}$ | 0.0078 |
| Q _g typ. (nC) | 15.5 |
| I _D (A) | 79.4 |
| Configuration | Single |

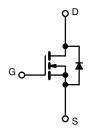
FEATURES

- TrenchFET® Gen IV power MOSFET
- Very low R_{DS} Q_g figure-of-merit (FOM)
- Tuned for the lowest R_{DS} Q_{oss} FOM
- 100 % R_a and UIS tested
- · Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

COMPLIANT HALOGEN **FREE**

APPLICATIONS

- Synchronous rectification
- · Primary side switch
- DC/DC converter
- · Motor drive switch



N-Channel MOSFET

| ORDERING INFORMATION | |
|---------------------------------|-----------------|
| Package | PowerPAK SO-8L |
| Lead (Pb)-free and halogen-free | SiJ186DP-T1-GE3 |

| ABSOLUTE MAXIMUM RATING | S (T _A = 25 °C, u | ınless otherw | vise noted) | | |
|--|-------------------------------------|-----------------------------------|----------------------|------|--|
| PARAMETER | | SYMBOL | LIMIT | UNIT | |
| Drain-source voltage | | V_{DS} | 60 | M | |
| Gate-source voltage | | V _{GS} | ± 20 | V | |
| Continuous drain current (T _J = 150 °C) | T _C = 25 °C | | 79.4 | | |
| | T _C = 70 °C | 1 . [| 63.5 | | |
| | T _A = 25 °C | I _D | 23 ^{b, c} | | |
| | T _A = 70 °C | 1 [| 18.4 ^{b, c} | • | |
| Pulsed drain current (t = 100 μs) | | I _{DM} | 150 | A | |
| Carting and a supply of the state of the sta | T _C = 25 °C | | 51.8 | | |
| Continuous source-drain diode current | T _A = 25 °C | l _s | 4.5 b, c | | |
| Single pulse avalanche current L = 0.1 mH | | I _{AS} | 25 | | |
| Single pulse avalanche energy | | E _{AS} | 31.25 | mJ | |
| | T _C = 25 °C | | 57 | | |
| Mandan and a sure discipation | T _C = 70 °C | 1 , [| 36 | W | |
| Maximum power dissipation | T _A = 25 °C | P _D | 5 b, c | VV | |
| | T _A = 70 °C | İ | 3.2 b, c | | |
| Operating junction and storage temperature range | | T _J , T _{stg} | -55 to +150 | °C | |
| Soldering recommendations (peak temperature) c | | | 260 | | |

| THERMAL RESISTANCE RAT | INGS | | | | |
|--|--------------|------------|---------|---------|------|
| PARAMETER | | SYMBOL | TYPICAL | MAXIMUM | UNIT |
| Maximum junction-to-ambient ^b | t ≤ 10 s | R_{thJA} | 20 | 25 | °C/W |
| Maximum junction-to-case (drain) | Steady state | R_{thJC} | 1.7 | 2.2 | C/VV |

Notes

- Package limited
 Surface mounted on 1" x 1" FR4 board

S18-0824-Rev. A, 13-Aug-2018

- See solder profile (www.vishay.com/doc?73257). The PowerPAK SO-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- Rework conditions: manual soldering with a soldering iron is not recommended for leadless components
- Maximum under steady state conditions is 70 °C/W $T_C = 25$ °C



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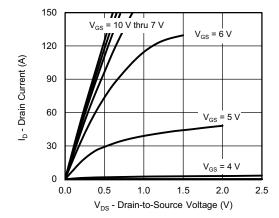
| PARAMETER | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNIT |
|---|---------------------------------------|--|--------------|--------|--------|-------|
| Static | | | | | | |
| Drain-source breakdown voltage | V _{DS} | V _{GS} = 0 V, I _D = 250 μA | 60 | - | - | V |
| V _{DS} temperature coefficient | $\Delta V_{DS}/T_{J}$ | I _D = 10 mA | - | 32 | - | |
| V _{GS(th)} temperature coefficient | $\Delta V_{GS(th)}/T_J$ | I _D = 250 μA | - | -6.7 | - | mV/°C |
| Gate-source threshold voltage | V _{GS(th)} | $V_{DS} = V_{GS}, I_D = 250 \mu A$ | 2 | - | 3.6 | V |
| Gate-source leakage | I _{GSS} | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$ | - | - | 100 | nA |
| | | $V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$ | - | - | 1 | |
| Zero gate voltage drain current | I _{DSS} | $V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 70 ^{\circ}\text{C}$ | - | - | 15 | μA |
| On-state drain current a | I _{D(on)} | $V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$ | 40 | - | - | Α |
| | | $V_{GS} = 10 \text{ V}, I_D = 15 \text{ A}$ | - | 0.0037 | 0.0045 | |
| Drain-source on-state resistance a | R _{DS(on)} | $V_{GS} = 7.5 \text{ V}, I_D = 10 \text{ A}$ | - | 0.0043 | 0.0054 | Ω |
| | | $V_{GS} = 6 \text{ V}, I_D = 10 \text{ A}$ | - | 0.0060 | 0.0078 | |
| Forward transconductance ^a | 9fs | V _{DS} = 15 V, I _D = 15 A | - | 54 | - | S |
| Dynamic ^b | | | | | | |
| Input capacitance | C _{iss} | | - | 1710 | | |
| Output capacitance | C _{oss} | $V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$ | - | 445 | - | рF |
| Reverse transfer capacitance | C _{rss} | | - | 29 | - | |
| <u> </u> | | $V_{DS} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 10 \text{ A}$ | - | 24.5 | 37 | |
| Total gate charge | Q _g | | - | 15.5 | 24 | _ |
| Gate-source charge | Q _{gs} | $V_{DS} = 30 \text{ V}, V_{GS} = 6 \text{ V}, I_D = 10 \text{ A}$ | - | 6.5 | - | nC |
| Gate-drain charge | Q _{gd} | 20 1 00 1 2 | - | 4.5 | - | _ |
| Output charge | Q _{oss} | $V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$ | - | 27.5 | - | _ |
| Gate resistance | R _q | f = 1 MHz | 0.3 | 0.85 | 1.5 | Ω |
| Turn-on delay time | t _{d(on)} | | - | 10 | 20 | |
| Rise time | t _r | $V_{DD} = 30 \text{ V}, R_L = 3 \Omega, I_D \cong 10 \text{ A},$ | _ | 22 | 44 | |
| Turn-off delay time | t _{d(off)} | $V_{GEN} = 10 \text{ V}, R_q = 1 \Omega$ | - | 14 | 28 | |
| Fall time | t _f | Ü | - | 9 | 18 | |
| Turn-on delay time | t _{d(on)} | | - | 11 | 22 | ns |
| Rise time | t _r | $V_{DD} = 30 \text{ V}, R_1 = 3 \Omega, I_D \cong 10 \text{ A},$ | - | 23 | 46 | _ |
| Turn-off delay time | t _{d(off)} | $V_{GEN} = 7.5 \text{ V}, R_q = 1 \Omega$ | _ | 13 | 26 | |
| Fall time | t _f | Ü | _ | 9 | 18 | |
| Drain-Source Body Diode Characteristi | · · · · · · · · · · · · · · · · · · · | | | ļ | | ļ |
| Continuous source-drain diode current | I _S | T _C = 25 °C | _ | _ | 51.8 | |
| Pulse diode forward current | I _{SM} | <u> </u> | _ | _ | 150 | Α |
| Body diode voltage | V _{SD} | I _S = 5 A, V _{GS} = 0 V | _ | 0.77 | 1.1 | V |
| Body diode reverse recovery time | t _{rr} | 15 - 5 / 1, vG5 - 0 v | - | 44 | 88 | ns |
| Body diode reverse recovery time | Q _{rr} | L = 10 A di/dt = 100 A/vo | - | 42 | 84 | nC |
| Reverse recovery fall time | t _a | $I_F = 10 \text{ A, di/dt} = 100 \text{ A/}\mu\text{s,}$ $T_{.1} = 25 ^{\circ}\text{C}$ | _ | 20 | 04 | 110 |
| | | | | | | 1 |

Notes

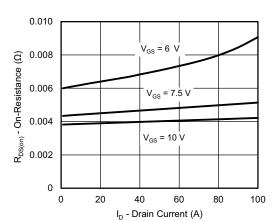
- a. Pulse test; pulse width $\leq 300~\mu\text{s},$ duty cycle $\leq 2~\%$
- b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

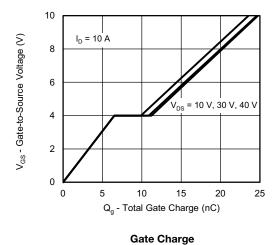




Output Characteristics

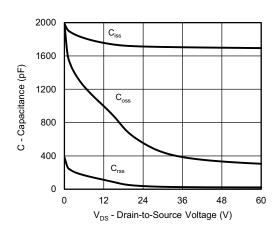


On-Resistance vs. Drain Current and Gate Voltage

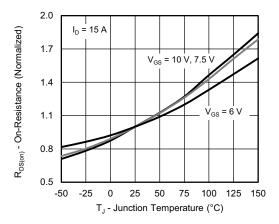


120
96
(Y) the true of the tru

Transfer Characteristics

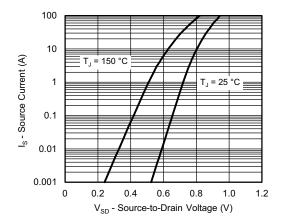


Capacitance

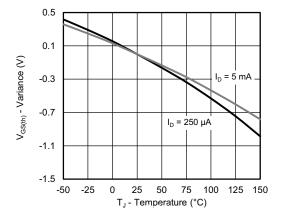


On-Resistance vs. Junction Temperature

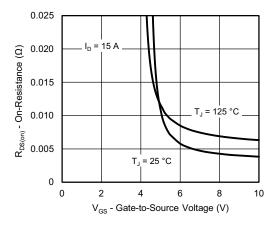




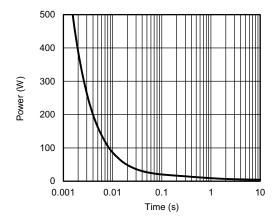
Source-Drain Diode Forward Voltage



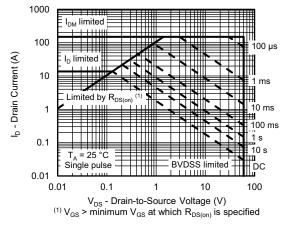
Threshold Voltage



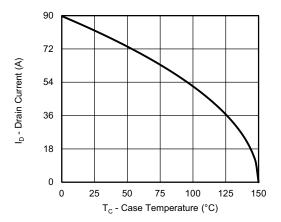
On-Resistance vs. Gate-to-Source Voltage



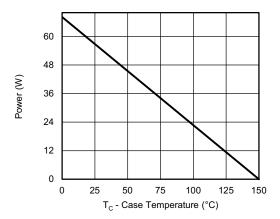
Single Pulse Power, Junction-to-Ambient



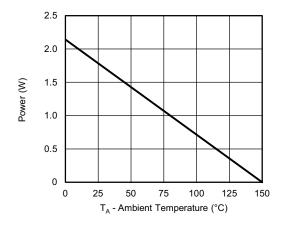
Safe Operating Area, Junction-to-Ambient



Current Derating a





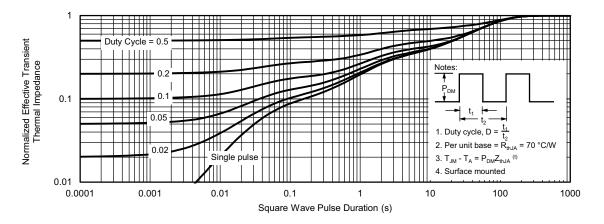


Power, Junction-to-Ambient

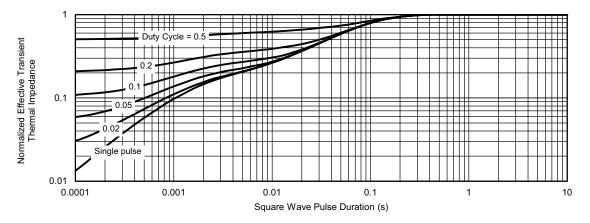
Note

a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





Normalized Thermal Transient Impedance, Junction-to-Ambient

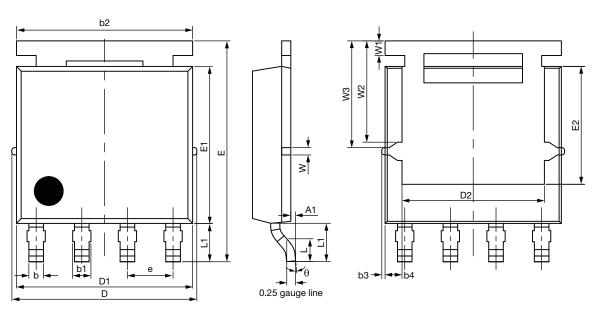


Normalized Thermal Transient Impedance, Junction-to-Case

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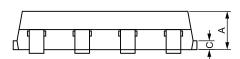


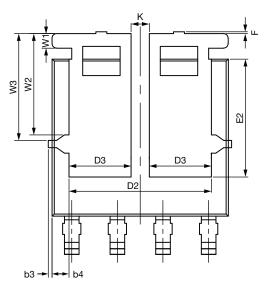
PowerPAK® SO-8L Case Outline 1



Topside view

Backside view (single)





Backside view (dual)



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| DIM. | MILLIMETERS | | | INCHES | | | |
|------|-------------|----------|-------|-----------|-------|-------|--|
| | MIN. | NOM. | MAX. | MIN. | NOM. | MAX. | |
| Α | 1.00 | 1.07 | 1.14 | 0.039 | 0.042 | 0.045 | |
| A1 | 0.00 | - | 0.127 | 0.00 | - | 0.005 | |
| b | 0.33 | 0.41 | 0.48 | 0.013 | 0.016 | 0.019 | |
| b1 | 0.44 | 0.51 | 0.58 | 0.017 | 0.020 | 0.023 | |
| b2 | 4.80 | 4.90 | 5.00 | 0.189 | 0.193 | 0.197 | |
| b3 | | 0.094 | • | | 0.004 | | |
| b4 | | 0.47 | | | 0.019 | | |
| С | 0.20 | 0.25 | 0.30 | 0.008 | 0.010 | 0.012 | |
| D | 5.00 | 5.13 | 5.25 | 0.197 | 0.202 | 0.207 | |
| D1 | 4.80 | 4.90 | 5.00 | 0.189 | 0.193 | 0.197 | |
| D2 | 3.86 | 3.96 | 4.06 | 0.152 | 0.156 | 0.160 | |
| D3 | 1.63 | 1.73 | 1.83 | 0.064 | 0.068 | 0.072 | |
| е | | 1.27 BSC | • | 0.050 BSC | | | |
| E | 6.05 | 6.15 | 6.25 | 0.238 | 0.242 | 0.246 | |
| E1 | 4.27 | 4.37 | 4.47 | 0.168 | 0.172 | 0.176 | |
| E2 | 3.18 | 3.28 | 3.38 | 0.125 | 0.129 | 0.133 | |
| F | - | - | 0.15 | - | - | 0.006 | |
| L | 0.62 | 0.72 | 0.82 | 0.024 | 0.028 | 0.032 | |
| L1 | 0.92 | 1.07 | 1.22 | 0.036 | 0.042 | 0.048 | |
| K | | 0.51 | | | 0.020 | | |
| W | 0.23 | | 0.009 | | | | |
| W1 | 0.41 | | 0.016 | | | | |
| W2 | 2.82 | | | 0.111 | | | |
| W3 | | 2.96 | | | 0.117 | | |
| θ | 0° | - | 10° | 0° | - | 10° | |

ECN: S19-0643-Rev. E, 05-Aug-2019

DWG: 5976

Note

• Millimeters will gover



RECOMMENDED MINIMUM PAD FOR PowerPAK® SO-8L SINGLE



Recommended Minimum Pads Dimensions in mm (inches)



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Vishay

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